

SHANGHAI SUNRISE ELECTRONICS CO., LTD.

US1A THRU US1M

SURFACE MOUNT ULTRA FAST SWITCHING RECTIFIER

TECHNICAL SPECIFICATION

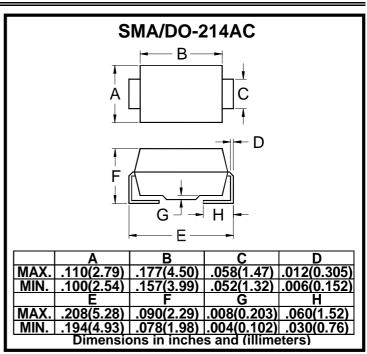
VOLTAGE: 50 TO 1000V CURRENT: 1.0A

FEATURES

- Ideal for surface mount pick and place application
- Low profile package
- Built-in strain relief
- High surge capability
- Glass passivated chip
- Ultra fast recovery for high efficiency
- High temperature soldering guaranteed: 260°C/10sec/at terminal

MECHANICAL DATA

- Terminal: Plated leads solderable per MIL-STD 202E, method 208C
- Case: Molded with UL-94 Class V-O recognized flame retardant epoxy
- · Polarity: Color band denotes cathode



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Single-phase, half-wave, 60Hz, resistive or inductive load rating at 25°C, unless otherwise stated, for capacitive load, derate current by 20%)

DATINGO	SYMBO	us.	US	US	US	US	US	US	LINUTO	
RATINGS)L 1A	1B	1D	1G	1J	1K	1M	UNITS	
Maximum Repetitive Peak Reverse Voltag	e V _{RRM}	50	100	200	400	600	800	1000	V	
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V	
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V	
Maximum Average Forward Rectified Curr	ent _I		1.0						Α	
$(T_L=100^{\circ}C)$	I _{F(AV)}		1.0							
Peak Forward Surge Current (8.3ms single	l _{FSM}		30						Α	
half sine-wave superimposed on rated load)										
Maximum Instantaneous Forward Voltage	ward Voltage		1.0 1.4			1.7			V	
(at rated forward current)	* F		1.0						•	
Maximum DC Reverse Current T _a =2	5°C		5.0						μΑ	
(at rated DC blocking voltage) T _a =10	0°C		200						μΑ	
Maximum Reverse Recovery Time (Not	e 1) trr		50				75			
Typical Junction Capacitance (Not	e 2) C _J		20			10			pF	
Typical Thermal Resistance (Not	e 3) R _θ (ja)		32				°C/W			
Storage and Operation Junction Temperato	ure T _{STG} ,T	J	-50 to +150						°C	
Note:										

- Note
- 1.Reverse recovery condition I_E=0.5A, I_R=1.0A,Irr=0.25A.
- 2.Measured at 1.0 MHz and applied voltage of $4.0V_{\rm dc}$
- 3. Thermal resistance from junction to terminal mounted on 5×5mm copper pad area